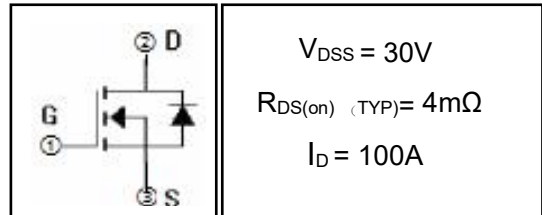


100A 30V N-channel Enhancement Mode Power MOSFET

1 Description

These N-channel Enhanced VDMOSFETs Used advanced trench technology design, provided excellent RDSON and low gate charge. Which accords with the RoHS standard.



2 Features

- Fast Switching
- Low ON Resistance($R_{dson} \leq 5.5m\Omega$)
- Low Gate Charge(Typical:43nC)
- Low Reverse Transfer Capacitance(Typical:215pF)
- 100% Single Pulse Avalanche Energy Test
- 100% ΔV_{DS} Test

3 Applications

- Power switching applications
- Inverter management system
- Electric Tools
- Automotive Electronics



4 Electrical Characteristics

4.1 Absolute Maximum Rating ($T_c=25^\circ C$, unless otherwise noted)

Parameter	Symbol	Value	Units	
Maximum Drain-Source DC Voltage	V_{DS}	30	V	
Maximum Gate-Drain Voltage	V_{GS}	± 20	V	
Drain Current(continuous)	$I_D (T=25^\circ C)$ $(T=100^\circ C)$	100	A	
		70	A	
Drain Current(Pulsed) ^(Note 1)	I_{DM}	280	A	
Single Pulse Avalanche Energy ^(Note 5)	E_{AS}	200	mJ	
Total Dissipation	$T_a=25^\circ C$	P_{tot}	1.25	W
	$T_c=25^\circ C$	P_{tot}	60	W
Junction Temperature	T_j	-55 ~ 150	$^\circ C$	
storage Temperature	T_{stg}	-55 ~ 150	$^\circ C$	
Maximum Temperature for soldering	T_L	300	$^\circ C$	

4.2 Thermal Characteristics

Parameter	Symbol	Value	Unit
Thermal Resistance Junction to Case-sink	R_{thJC}	2.08	$^\circ C/W$
Thermal Resistance Junction to Ambient	R_{thJA}	100	$^\circ C/W$

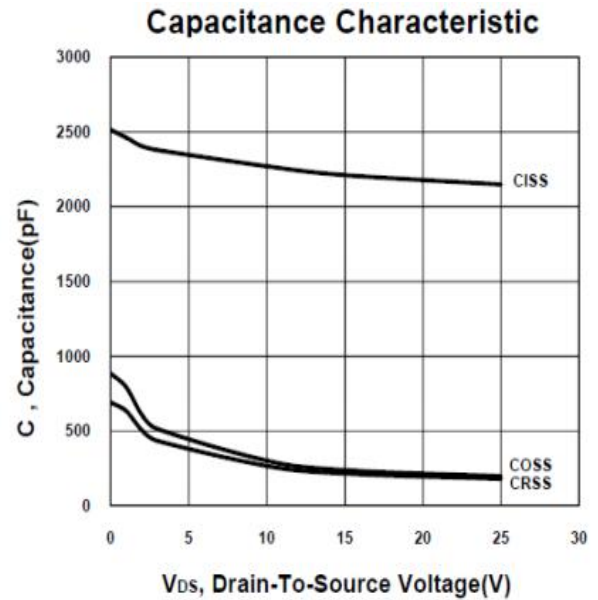
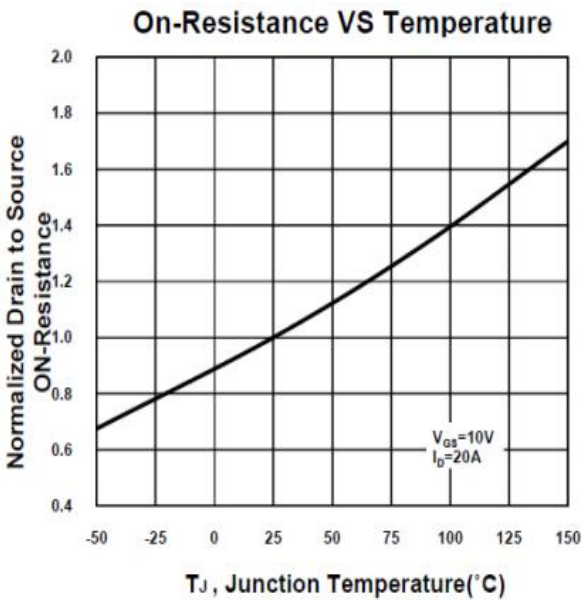
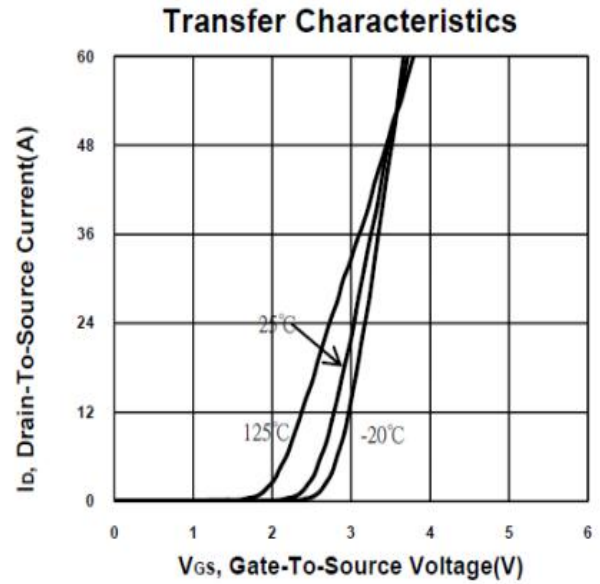
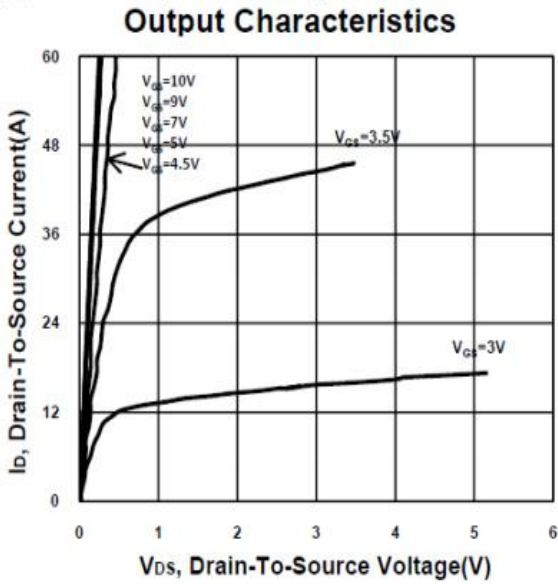
4.3 Electrical Characteristics (T_c=25°C, unless otherwise noted)

Parameter	Symbol	Test Condition	Value			Units
			Min	Typ	Max	
Off Characteristics						
Drain-source Breakdown Voltage	BV _{DSS}	I _D =250μA, V _{GS} =0V	30	--	--	V
Drain-to-Source Leakage Current	I _{DSS}	V _{DS} =30V, V _{GS} =0V, T _C =25°C	--	--	1	μA
		V _{DS} =24V, V _{GS} =0V, T _C =125°C	--	--	100	μA
Gate-to-Source Forward Leakage	I _{GSSF}	V _{GS} =+20V	--	--	100	nA
Gate-to-Source Reverse Leakage	I _{GSSR}	V _{GS} =-20V	--	--	-100	nA
On Characteristics (Note 3)						
Gate threshold voltage	V _{GS(th)}	V _{DS} =V _{GS} , I _D =250μA	1	1.7	3	V
Drain-source on Resistance	R _{DS(on)}	V _{GS} =10V, I _D =20A	--	4	5.5	mΩ
		V _{GS} =4.5V, I _D =20A	--	7.5	9	
Dynamic Characteristics (Note 4)						
Input Capacitance	C _{iss}	V _{GS} =0V, V _{DS} =30V, f=1.0MHz	--	2250	--	pF
Output Capacitance	C _{oss}		--	235	--	
Reverse Transfer Capacitance	C _{rss}		--	215	--	
Gate Resistance	R _G	V _{GS} =0V, V _{DS} =0V, f=1.0MHz	--	1.3	--	Ω
Switching Characteristics (note4)						
Turn-on Delay Time	t _{d(on)}	V _{DS} =12.5V, R _L =30Ω, V _{GS} =10V, R _{GEN} =6Ω	--	16	--	nS
Turn-on Rise Time	t _r		--	15	--	
Turn-off Delay Time	t _{d(off)}		--	55	--	
Turn-off Fall Time	t _f		--	25	--	
Total Gate Charge	Q _g	I _D =20A, V _{DS} =12.5V, V _{GS} =10V	--	43	--	nC
Gate-to-Source Charge	Q _{gs}		--	7.5	--	
Gate-to-Drain("Miller") Charge	Q _{gd}		--	10.6	--	
Drain-Source Diode Characteristics						
Diode Forward Voltage (Note 3)	V _{FSD}	V _{GS} =0V, I _S =20A	--	0.9	1.3	V
Diode Forward Current (Note 2)	I _S		--	--	100	A
Reverse Recovery Time	t _{rr}	T _J =25°C, I _F =20A, di _F /dt=100A/μS, V _{GS} =0V	--	35	--	nS
Reverse Recovery Charge	Q _{rr}		--	23	--	nC

Notes:

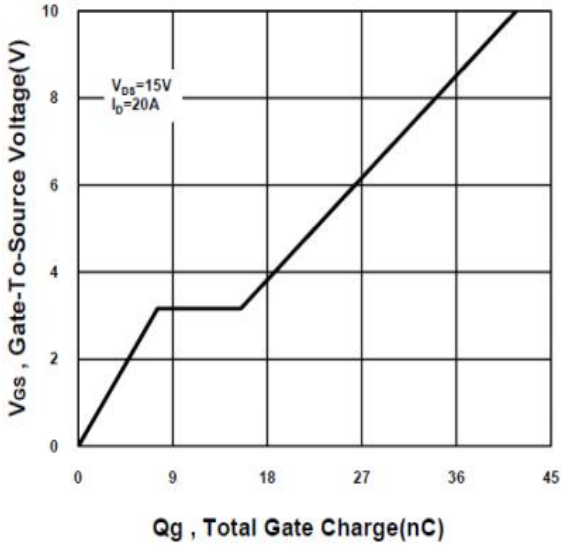
- 1: Repetitive rating, pulse width limited by maximum junction temperature.
- 2: Surface mounted on FR4 Board, t_s≤10sec.
- 3: Pulse width ≤ 300μs, duty cycle ≤ 2%.
- 4: Guaranteed by design, not subject to production.
- 5: L=0.5mH, I_D=8A, V_{DD}=50V, V_{GATE}=100V, Start T_J=25°C.

5 Typical characteristics diagrams

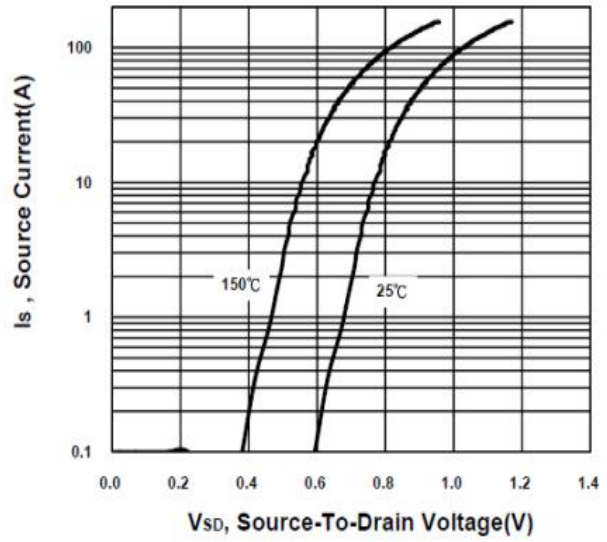


5 Typical characteristics diagrams(continues)

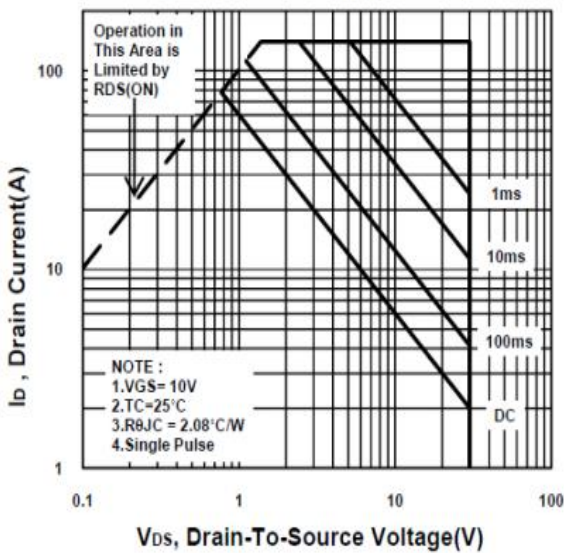
Gate charge Characteristics



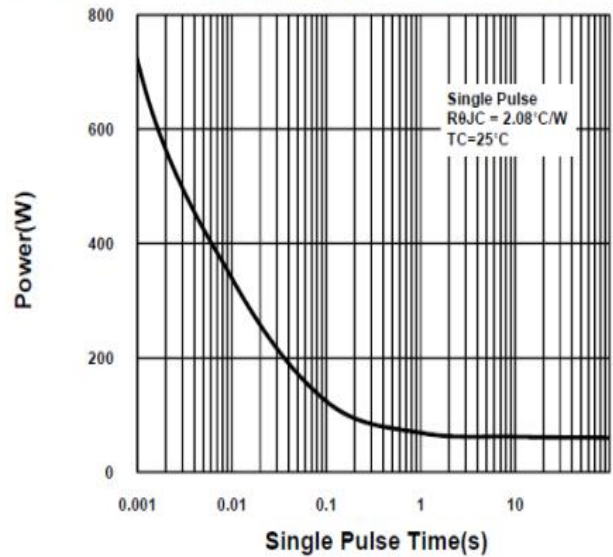
Source-Drain Diode Forward Voltage



Safe Operating Area

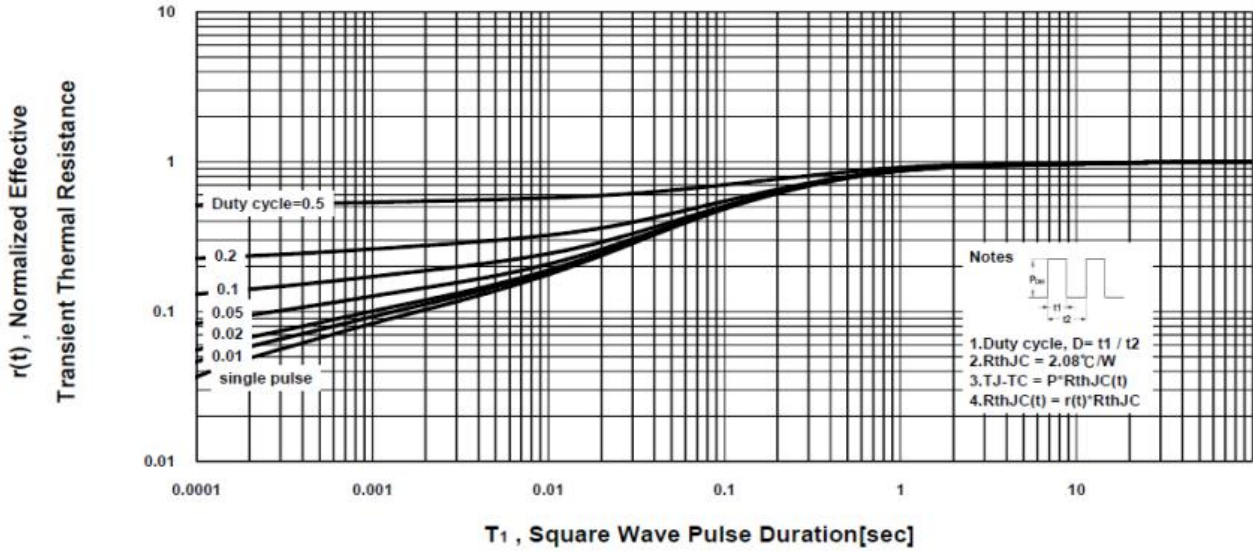


Single Pulse Maximum Power Dissipation



5 Typical characteristics diagrams(continues)

Transient Thermal Response Curve



6 Typical Test Circuit and Waveform

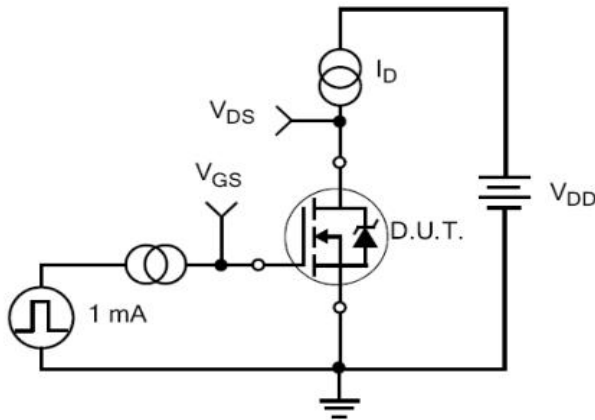


Figure 17. Gate Charge Test Circuit

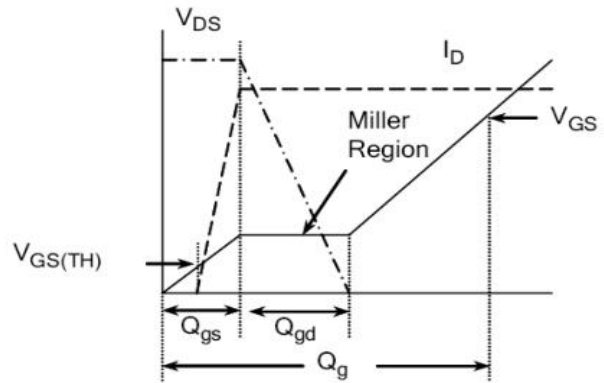


Figure 18. Gate Charge Waveform

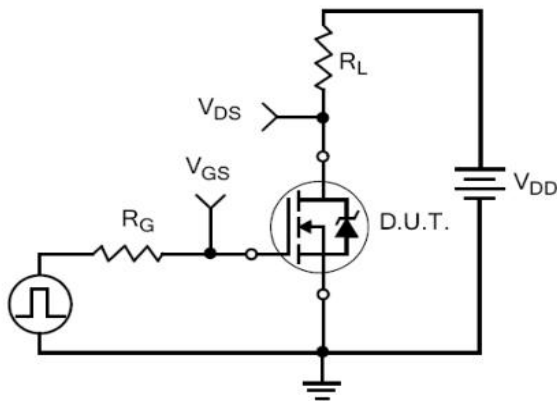


Figure 19. Resistive Switching Test Circuit

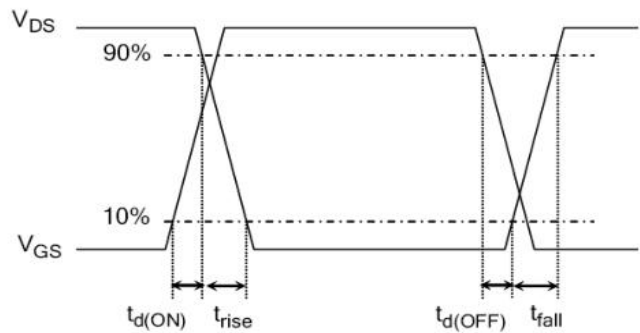


Figure 20. Resistive Switching Waveforms

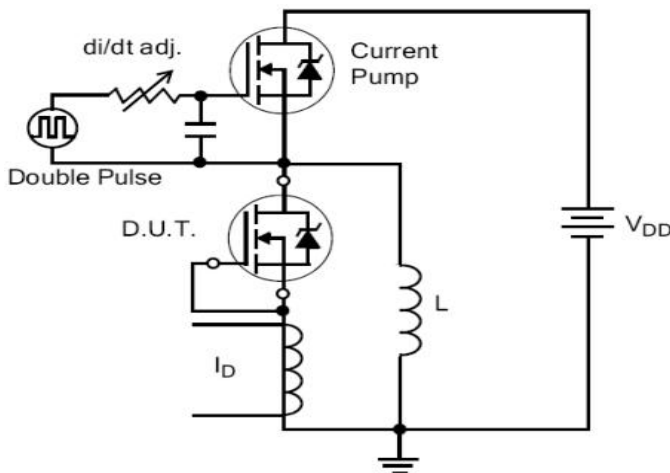


Figure 21. Diode Reverse Recovery Test Circuit

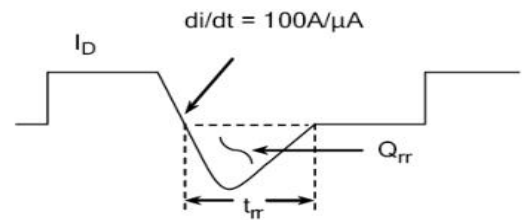


Figure 22. Diode Reverse Recovery Waveform

6 Typical Test Circuit and Waveform(continues)

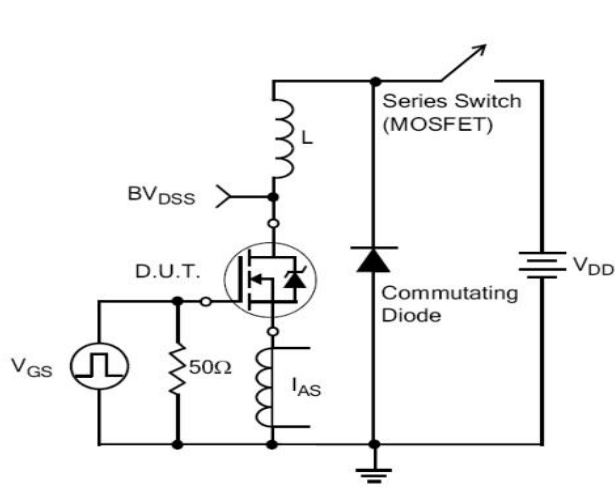


Figure 23. Unclamped Inductive Switching Test Circuit

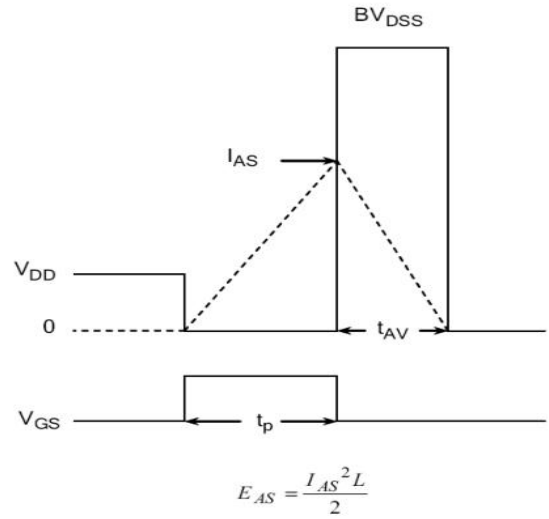


Figure 24. Unclamped Inductive Switching Waveforms

7 Product Names Rules

F X X N E X X

Packaging Code
220F: F 220: Nothing
251: B 252: D
262: I 263: E

Rated Voltage Code
With 2 Digital, For Example:
60 on behalf of 600V,
06 on behalf of 60v

Rated Current Code
With 1-2 Digital,
For Example:
4 on behalf of 4A,
10 on behalf of 10A,
08 on behalf of 0.8A

Special Function Code
E on behalf of build-in ESD
Nothing on behalf of not ESD

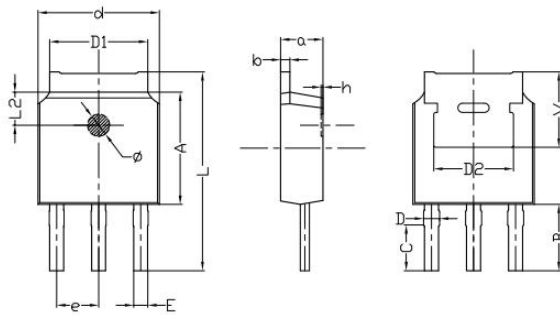
Channel Polarity Code
N on behalf of N channel
P on behalf of P channel

8 Product Specifications and Packaging Models

Product Model	Package Type	Mark Name	RoHS	Package	Quantity
30H10I	TO-251	30H10I	Pb-free	Tube	3000/box
30H10K	TO-252	30H10K	Pb-free	Tape & Reel	2500/box

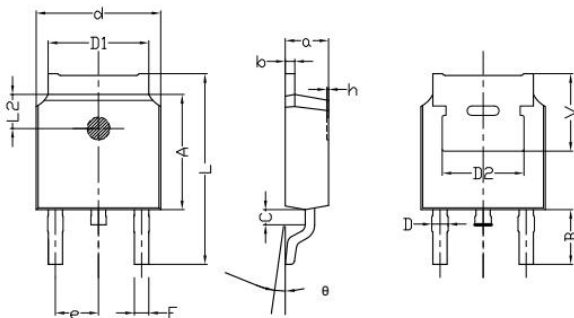
9 Dimensions

TO-251B PACKAGE OUTLINE DIMENSIONS



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	min.	max.	min.	max.
a	2.20	2.40	0.087	0.0946
b	0.46	0.58	0.018	0.023
C	2.45	2.65	0.097	0.104
D	0.80	0.90	0.032	0.035
d	6.30	6.70	0.248	0.264
D1	5.00	5.50	0.197	0.217
D2	TYP 4.83		TYP 0.190	
A	5.80	6.20	0.228	0.244
e	2.19	2.39	0.086	0.094
L	10.40	11.00	0.4098	0.4334
B	3.50	3.70	0.1379	0.1458
L2	1.5	1.8	0.059	0.071
φ	1.10	1.30	0.0433	0.0512
h	0.00	0.30	0.000	0.012
V	5.25	5.85	0.207	0.230
E	0.60	0.80	0.0236	0.0315

TO-252B PACKAGE OUTLINE DIMENSIONS



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	min.	max.	min.	max.
a	2.20	2.40	0.087	0.095
b	0.46	0.58	0.018	0.023
c	0.70	0.90	0.028	0.035
D	0.80	1.00	0.032	0.039
d	6.30	6.70	0.248	0.264
D1	5.00	5.50	0.197	0.217
D2	TYP 4.83		TYP 0.190	
A	5.80	6.20	0.228	0.244
e	2.19	2.39	0.086	0.094
L	9.40	10.40	0.370	0.409
B	2.6	3.2	0.102	0.126
L2	1.5	1.8	0.059	0.071
θ	0	8	0	8
h	0	0.3	0	0.012
V	5.25	5.85	0.207	0.230

10 Attentions

- ROUM Semiconductor Technology CO.,LTD. reserves the right to change the specification without prior notice! The customer should obtain the latest version of the information before making the order and verify that the information is complete and up to date.
- It is the responsibility of the purchaser for any failure or failure of any semiconductor product under certain conditions. It is the responsibility of the purchaser to comply with safety standards and to take safety measures in the system design and machine manufacturing of Roma products in order to avoid potential risk of failure. Injury or property damage.
- Product promotion is endless, our company will be dedicated to provide customers with better products.

11 Appendix

Revision history:

Date	REV.	Description	Page
2017.05.15	1.0	Original	